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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In-System Reprogrammable™ (ISR™) CMOS
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	128
Number of Gates	-
Number of I/O	133
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-LQFP
Supplier Device Package	160-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy37128p160-125axc

Speed Bins

Device	200	167	154	143	125	100	83	66
CY37032V				X		X		
CY37064V				X		X		
CY37128V					X		X	
CY37192V						X		X
CY37256V						X		X
CY37384V							X	X
CY37512V							X	X

Device-Package Offering and I/O Count

Device	44-Lead TQFP	44-Lead CLCC	48-Lead FBGA	84-Lead CLCC	100-Lead TQFP	100-Lead FBGA	160-Lead TQFP	160-Lead CQFP	208-Lead PQFP	208-Lead CQFP	292-Lead PBGA	256-Lead FBGA	388-Lead PBGA	400-Lead FBGA
CY37032V	37		37											
CY37064V	37	37	37		69	69								
CY37128V				69	69	85	133							
CY37192V							125							
CY37256V							133	133	165		197	197		
CY37384V									165		197			
CY37512V									165	165	197		269	269

Architecture Overview of Ultra37000 Family
Programmable Interconnect Matrix

The PIM consists of a completely global routing matrix for signals from I/O pins and feedbacks from the logic blocks. The PIM provides extremely robust interconnection to avoid fitting and density limitations.

The inputs to the PIM consist of all I/O and dedicated input pins and all macrocell feedbacks from within the logic blocks. The number of PIM inputs increases with pin count and the number of logic blocks. The outputs from the PIM are signals routed to the appropriate logic blocks. Each logic block receives 36 inputs from the PIM and their complements, allowing for 32-bit operations to be implemented in a single pass through the device. The wide number of inputs to the logic block also improves the routing capacity of the Ultra37000 family.

An important feature of the PIM is its simple timing. The propagation delay through the PIM is accounted for in the timing specifications for each device. There is no additional delay for traveling through the PIM. In fact, all inputs travel through the PIM. As a result, there are no route-dependent timing parameters on the Ultra37000 devices. The worst-case PIM delays are incorporated in all appropriate Ultra37000 specifications.

Routing signals through the PIM is completely invisible to the user. All routing is accomplished by software—no hand routing is necessary. *Warp*® and third-party development packages automatically route designs for the Ultra37000 family in a matter of minutes. Finally, the rich routing resources of the Ultra37000 family accommodate last minute logic changes while maintaining fixed pin assignments.

Logic Block

The logic block is the basic building block of the Ultra37000 architecture. It consists of a product term array, an intelligent product-term allocator, 16 macrocells, and a number of I/O cells. The number of I/O cells varies depending on the device used. Refer to *Figure 1* for the block diagram.

Product Term Array

Each logic block features a 72 x 87 programmable product term array. This array accepts 36 inputs from the PIM, which originate from macrocell feedbacks and device pins. Active LOW and active HIGH versions of each of these inputs are generated to create the full 72-input field. The 87 product terms in the array can be created from any of the 72 inputs.

Of the 87 product terms, 80 are for general-purpose use for the 16 macrocells in the logic block. Four of the remaining seven product terms in the logic block are output enable (OE) product terms. Each of the OE product terms controls up to eight of the 16 macrocells and is selectable on an individual macrocell basis. In other words, each I/O cell can select between one of two OE product terms to control the output buffer. The first two of these four OE product terms are available to the upper half of the I/O macrocells in a logic block. The other two OE product terms are available to the lower half of the I/O macrocells in a logic block.

The next two product terms in each logic block are dedicated asynchronous set and asynchronous reset product terms. The final product term is the product term clock. The set, reset, OE and product term clock have polarity control to realize OR functions in a single pass through the array.

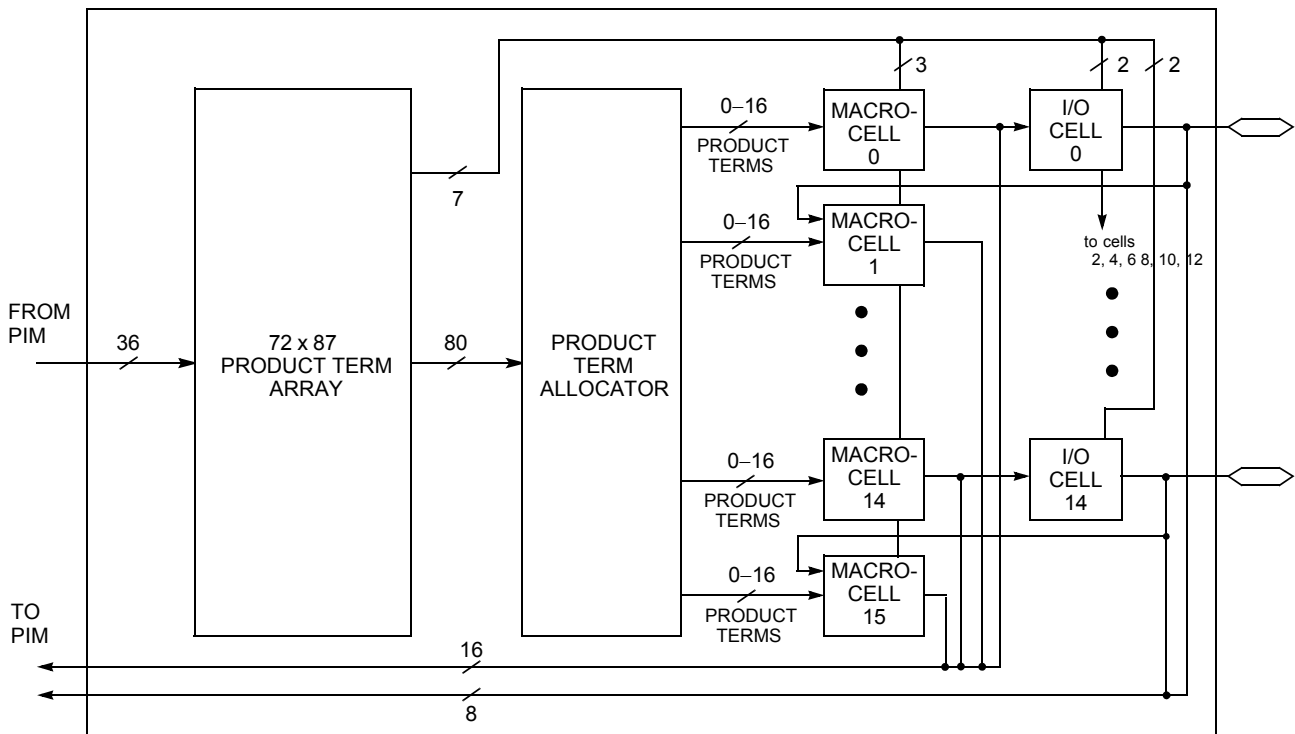


Figure 1. Logic Block with 50% Buried Macrocells

Low-Power Option

Each logic block can operate in high-speed mode for critical path performance, or in low-power mode for power conservation. The logic block mode is set by the user on a logic block basis.

Product Term Allocator

Through the product term allocator, software automatically distributes product terms among the 16 macrocells in the logic block as needed. A total of 80 product terms are available from the local product term array. The product term allocator provides two important capabilities without affecting performance: product term steering and product term sharing.

Product Term Steering

Product term steering is the process of assigning product terms to macrocells as needed. For example, if one macrocell requires ten product terms while another needs just three, the product term allocator will “steer” ten product terms to one macrocell and three to the other. On Ultra37000 devices, product terms are steered on an individual basis. Any number between 0 and 16 product terms can be steered to any macrocell. Note that 0 product terms is useful in cases where a particular macrocell is unused or used as an input register.

Product Term Sharing

Product term sharing is the process of using the same product term among multiple macrocells. For example, if more than one output has one or more product terms in its equation that are common to other outputs, those product terms are only programmed once. The Ultra37000 product term allocator allows sharing across groups of four output macrocells in a

variable fashion. The software automatically takes advantage of this capability—the user does not have to intervene.

Note that neither product term sharing nor product term steering have any effect on the speed of the product. All worst-case steering and sharing configurations have been incorporated in the timing specifications for the Ultra37000 devices.

Ultra37000 Macrocell

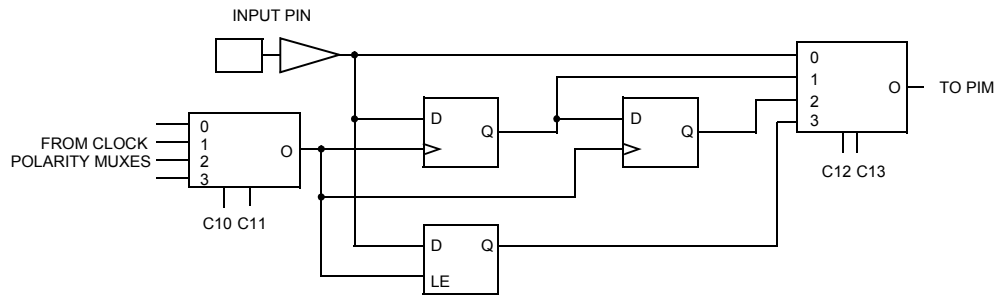
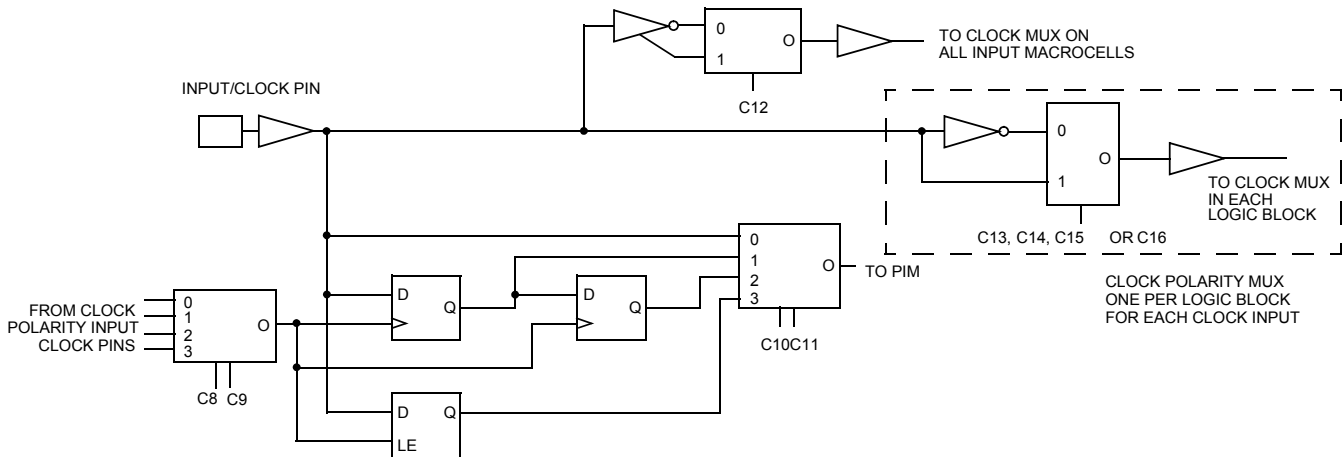
Within each logic block there are 16 macrocells. Macrocells can either be I/O Macrocells, which include an I/O Cell which is associated with an I/O pin, or buried Macrocells, which do not connect to an I/O. The combination of I/O Macrocells and buried Macrocells varies from device to device.

Buried Macrocell

Figure 2 displays the architecture of buried macrocells. The buried macrocell features a register that can be configured as combinatorial, a D flip-flop, a T flip-flop, or a level-triggered latch.

The register can be asynchronously set or asynchronously reset at the logic block level with the separate set and reset product terms. Each of these product terms features programmable polarity. This allows the registers to be set or reset based on an AND expression or an OR expression.

Clocking of the register is very flexible. Four global synchronous clocks and a product term clock are available to clock the register. Furthermore, each clock features programmable polarity so that registers can be triggered on falling as well as rising edges (see the Clocking section). Clock polarity is chosen at the logic block level.


Figure 3. Input Macrocell

Figure 4. Input/Clock Macrocell

Clocking

Each I/O and buried macrocell has access to four synchronous clocks (CLK0, CLK1, CLK2 and CLK3) as well as an asynchronous product term clock PTCLK. Each input macrocell has access to all four synchronous clocks.

Dedicated Inputs/Clocks

Five pins on each member of the Ultra37000 family are designated as input-only. There are two types of dedicated inputs on Ultra37000 devices: input pins and input/clock pins. *Figure 3* illustrates the architecture for input pins. Four input options are available for the user: combinatorial, registered, double-registered, or latched. If a registered or latched option is selected, any one of the input clocks can be selected for control.

Figure 4 illustrates the architecture for the input/clock pins. Like the input pins, input/clock pins can be combinatorial, registered, double-registered, or latched. In addition, these pins feed the clocking structures throughout the device. The clock path at the input has user-configurable polarity.

Product Term Clocking

In addition to the four synchronous clocks, the Ultra37000 family also has a product term clock for asynchronous clocking. Each logic block has an independent product term clock which is available to all 16 macrocells. Each product term clock also supports user configurable polarity selection.

Timing Model

One of the most important features of the Ultra37000 family is the simplicity of its timing. All delays are worst case and system performance is unaffected by the features used. *Figure 5* illustrates the true timing model for the 167-MHz devices in high speed mode. For combinatorial paths, any input to any output incurs a 6.5-ns worst-case delay regardless of the amount of logic used. For synchronous systems, the input set-up time to the output macrocells for any input is 3.5 ns and the clock to output time is also 4.0 ns. These measurements are for any output and synchronous clock, regardless of the logic used.

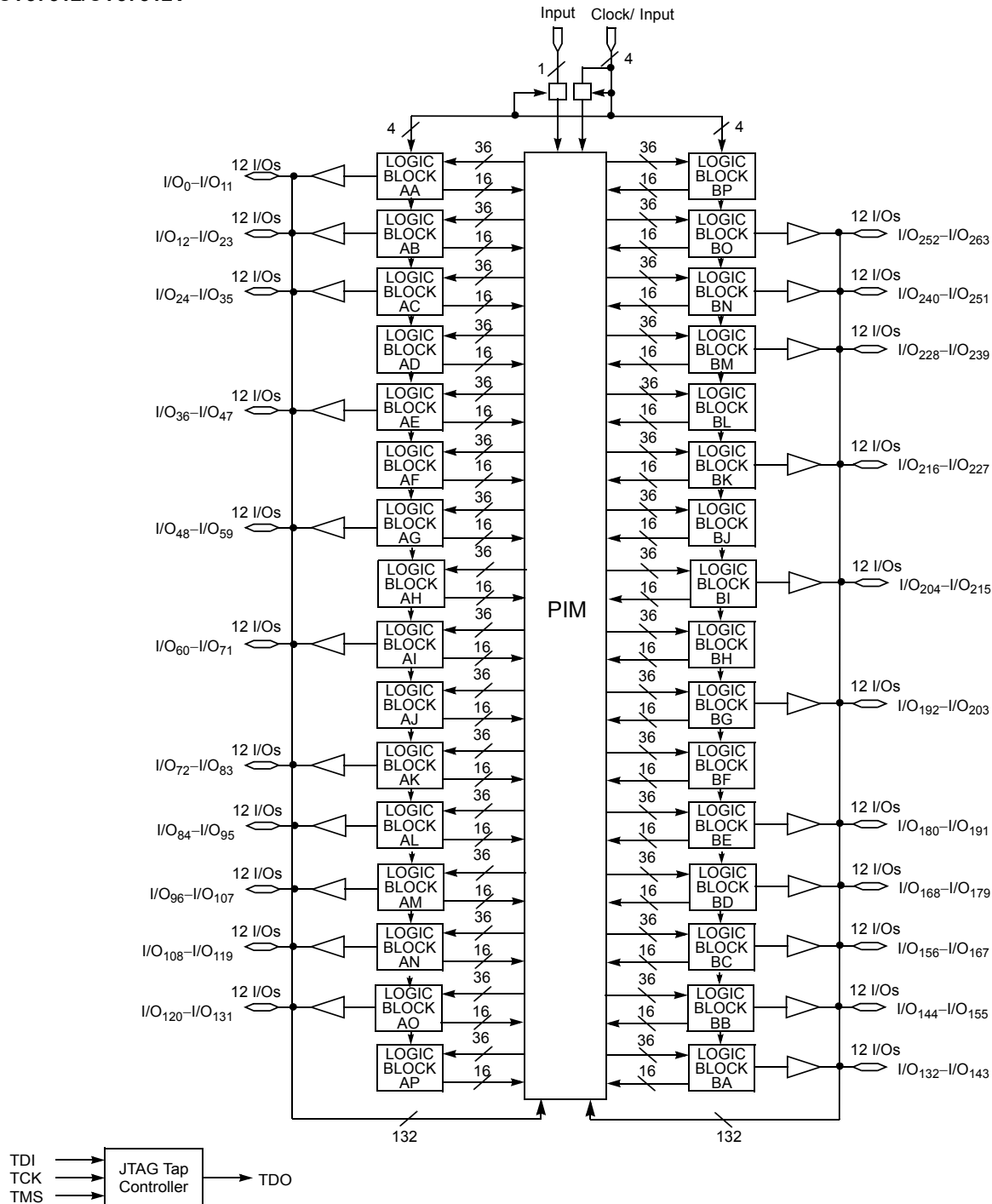
The Ultra37000 features:

- No fanout delays
- No expander delays
- No dedicated vs. I/O pin delays
- No additional delay through PIM
- No penalty for using 0–16 product terms
- No added delay for steering product terms
- No added delay for sharing product terms
- No routing delays
- No output bypass delays

The simple timing model of the Ultra37000 family eliminates unexpected performance penalties.

Logic Block Diagrams (continued)

CY37512/CY37512V



5.0V Device Characteristics

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with

Power Applied -55°C to +125°C

Supply Voltage to Ground Potential -0.5V to +7.0V

DC Voltage Applied to Outputs

in High-Z State -0.5V to +7.0V

DC Input Voltage -0.5V to +7.0V

DC Program Voltage 4.5 to 5.5V

Current into Outputs 16 mA

Static Discharge Voltage > 2001V
(per MIL-STD-883, Method 3015)

Latch-up Current > 200 mA

Operating Range^[2]

Range	Ambient Temperature ^[2]	Junction Temperature	Output Condition	V _{CC}	V _{CCO}
Commercial	0°C to +70°C	0°C to +90°C	5V	5V ± 0.25V	5V ± 0.25V
			3.3V	5V ± 0.25V	3.3V ± 0.3V
Industrial	-40°C to +85°C	-40°C to +105°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V
Military ^[3]	-55°C to +125°C	-55°C to +130°C	5V	5V ± 0.5V	5V ± 0.5V
			3.3V	5V ± 0.5V	3.3V ± 0.3V

5.0V Device Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min. I _{OH} = -3.2 mA (Com'I/Ind) ^[4] I _{OH} = -2.0 mA (Mil) ^[4]	2.4 2.4			V
V _{OHZ}	Output HIGH Voltage with Output Disabled ^[5]	V _{CC} = Max. I _{OH} = 0 μA (Com'I) ^[6] I _{OH} = 0 μA (Ind/Mil) ^[6] I _{OH} = -100 μA (Com'I) ^[6] I _{OH} = -150 μA (Ind/Mil) ^[6]			4.2 4.5 3.6 3.6	V
V _{OL}	Output LOW Voltage	V _{CC} = Min. I _{OL} = 16 mA (Com'I/Ind) ^[4] I _{OL} = 12 mA (Mil) ^[4]			0.5 0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs ^[7]	2.0		V _{CCmax}	V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs ^[7]	-0.5		0.8	V
I _{IX}	Input Load Current	V _I = GND OR V _{CC} , Bus-Hold Disabled	-10		10	μA
I _{OZ}	Output Leakage Current	V _O = GND or V _{CC} , Output Disabled, Bus-Hold Disabled	-50		50	μA
I _{OS}	Output Short Circuit Current ^[5, 8]	V _{CC} = Max., V _{OUT} = 0.5V	-30		-160	mA
I _{BHL}	Input Bus-Hold LOW Sustaining Current	V _{CC} = Min., V _{IL} = 0.8V	+75			μA
I _{BHH}	Input Bus-Hold HIGH Sustaining Current	V _{CC} = Min., V _{IH} = 2.0V	-75			μA
I _{BHLO}	Input Bus-Hold LOW Overdrive Current	V _{CC} = Max.			+500	μA
I _{BHHO}	Input Bus-Hold HIGH Overdrive Current	V _{CC} = Max.			-500	μA

Notes:

- Normal Programming Conditions apply across Ambient Temperature Range for specified programming methods. For more information on programming the Ultra37000 Family devices, please refer to the Application Note titled "An Introduction to In System Reprogramming with the Ultra37000."
- T_A is the "Instant On" case temperature.
- I_{OH} = -2 mA, I_{OL} = 2 mA for TDO.
- Tested initially and after any design or process changes that may affect these parameters.
- When the I/O is output disabled, the bus-hold circuit can weakly pull the I/O to above 3.6V if no leakage current is allowed. Note that all I/Os are output disabled during ISR programming. Refer to the application note "Understanding Bus-Hold" for additional information.
- These are absolute values with respect to device ground. All overshoots due to system or tester noise are included.
- Not more than one output should be tested at a time. Duration of the short circuit should not exceed 1 second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.

Inductance^[5]

Parameter	Description	Test Conditions	44-Lead TQFP	44-Lead PLCC	44-Lead CLCC	84-Lead PLCC	84-Lead CLCC	100-Lead TQFP	160-Lead TQFP	208-Lead PQFP	Unit
L	Maximum Pin Inductance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$	2	5	2	8	5	8	9	11	nH

Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
$C_{I/O}$	Input/Output Capacitance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	10	pF
C_{CLK}	Clock Signal Capacitance	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	12	pF
C_{DP}	Dual-Function Pins ^[9]	$V_{IN} = 5.0V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	16	pF

Endurance Characteristics^[5]

Parameter	Description	Test Conditions	Min.	Typ.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions ^[2]	1,000	10,000	Cycles

3.3V Device Characteristics
Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature $-65^\circ C$ to $+150^\circ C$

Ambient Temperature with

Power Applied $-55^\circ C$ to $+125^\circ C$

Supply Voltage to Ground Potential $-0.5V$ to $+4.6V$

DC Voltage Applied to Outputs

in High-Z State $-0.5V$ to $+7.0V$

DC Input Voltage $-0.5V$ to $+7.0V$

DC Program Voltage 3.0 to $3.6V$

Current into Outputs 8 mA

Static Discharge Voltage $> 2001V$
(per MIL-STD-883, Method 3015)

Latch-up Current $> 200\text{ mA}$

Operating Range^[2]

Range	Ambient Temperature ^[2]	Junction Temperature	V_{CC} ^[10]
Commercial	$0^\circ C$ to $+70^\circ C$	$0^\circ C$ to $+90^\circ C$	$3.3V \pm 0.3V$
Industrial	$-40^\circ C$ to $+85^\circ C$	$-40^\circ C$ to $+105^\circ C$	$3.3V \pm 0.3V$
Military ^[3]	$-55^\circ C$ to $+125^\circ C$	$-55^\circ C$ to $+130^\circ C$	$3.3V \pm 0.3V$

3.3V Device Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $I_{OH} = -4\text{ mA (Com'I)}^{[4]}$ $I_{OH} = -3\text{ mA (Mil)}^{[4]}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$ $I_{OL} = 8\text{ mA (Com'I)}^{[4]}$ $I_{OL} = 6\text{ mA (Mil)}^{[4]}$		0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs ^[7]	2.0	5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs ^[7]	-0.5	0.8	V
I_{IX}	Input Load Current	$V_I = \text{GND OR } V_{CC}$, Bus-Hold Disabled	-10	10	μA
I_{OZ}	Output Leakage Current	$V_O = \text{GND or } V_{CC}$, Output Disabled, Bus-Hold Disabled	-50	50	μA
I_{OS}	Output Short Circuit Current ^[5, 8]	$V_{CC} = \text{Max.}$, $V_{OUT} = 0.5V$	-30	-160	mA
I_{BHL}	Input Bus-Hold LOW Sustaining Current	$V_{CC} = \text{Min.}$, $V_{IL} = 0.8V$	+75		μA
I_{BHH}	Input Bus-Hold HIGH Sustaining Current	$V_{CC} = \text{Min.}$, $V_{IH} = 2.0V$	-75		μA
I_{BHLO}	Input Bus-Hold LOW Overdrive Current	$V_{CC} = \text{Max.}$		+500	μA
I_{BHHO}	Input Bus-Hold HIGH Overdrive Current	$V_{CC} = \text{Max.}$		-500	μA

Notes:

9. Dual pins are I/O with JTAG pins.

10. For CY37064VP100-143AC, CY37064VP100-143BBC, CY37064VP44-143AC, CY37064VP48-143BAC; Operating Range: V_{CC} is $3.3V \pm 0.16V$.

Inductance^[5]

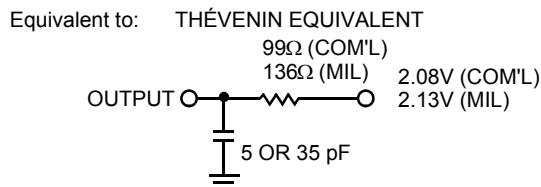
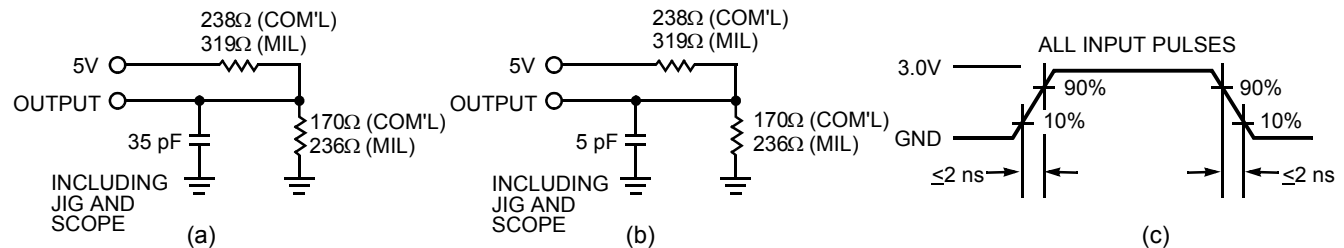
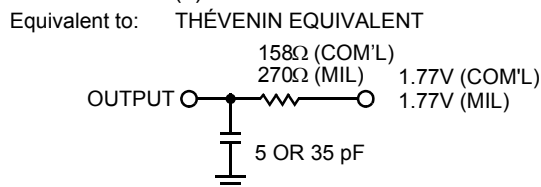
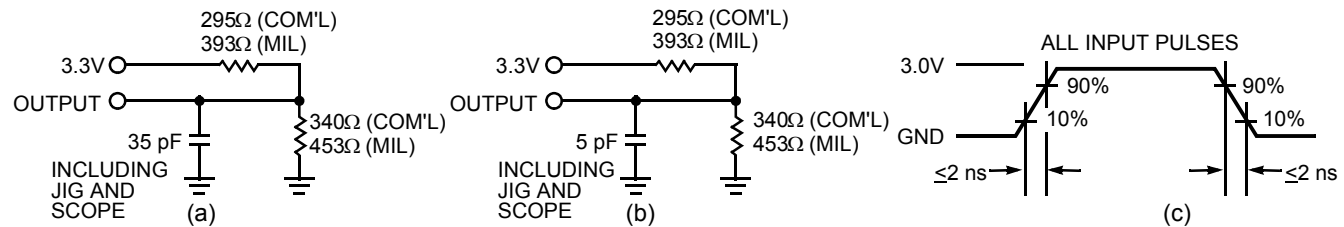
Parameter	Description	Test Conditions	44-Lead TQFP	44-Lead PLCC	44-Lead CLCC	84-Lead PLCC	84-Lead CLCC	100-Lead TQFP	160-Lead TQFP	208-Lead PQFP	Unit
L	Maximum Pin Inductance	$V_{IN} = 3.3V$ at $f = 1\text{ MHz}$	2	5	2	8	5	8	9	11	nH

Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
$C_{I/O}$	Input/Output Capacitance	$V_{IN} = 3.3V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	8	pF
C_{CLK}	Clock Signal Capacitance	$V_{IN} = 3.3V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	12	pF
C_{DP}	Dual Functional Pins ^[9]	$V_{IN} = 3.3V$ at $f = 1\text{ MHz}$ at $T_A = 25^\circ C$	16	pF

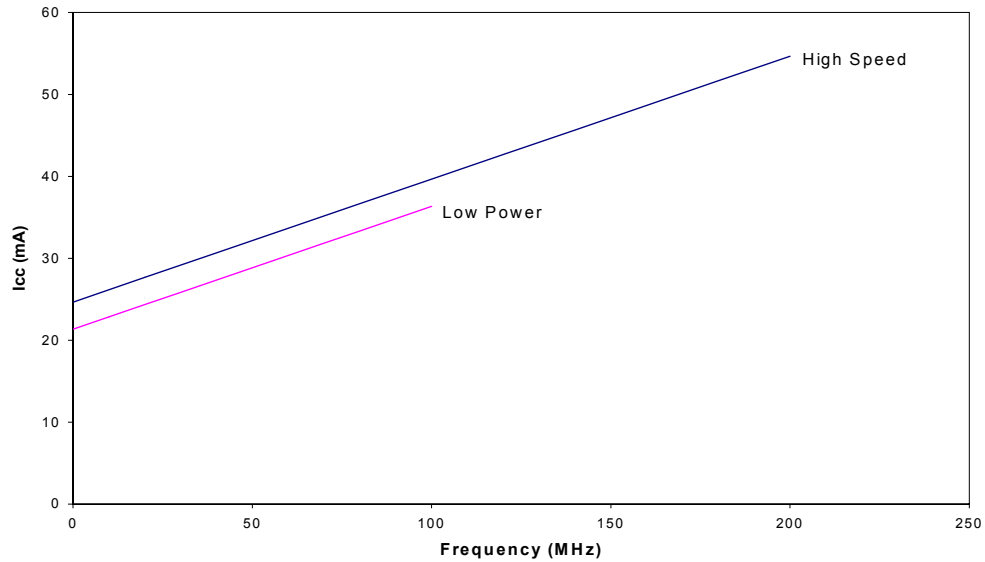
Endurance Characteristics^[5]

Parameter	Description	Test Conditions	Min.	Typ.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions ^[2]	1,000	10,000	Cycles

AC Characteristics
5.0V AC Test Loads and Waveforms

3.3V AC Test Loads and Waveforms


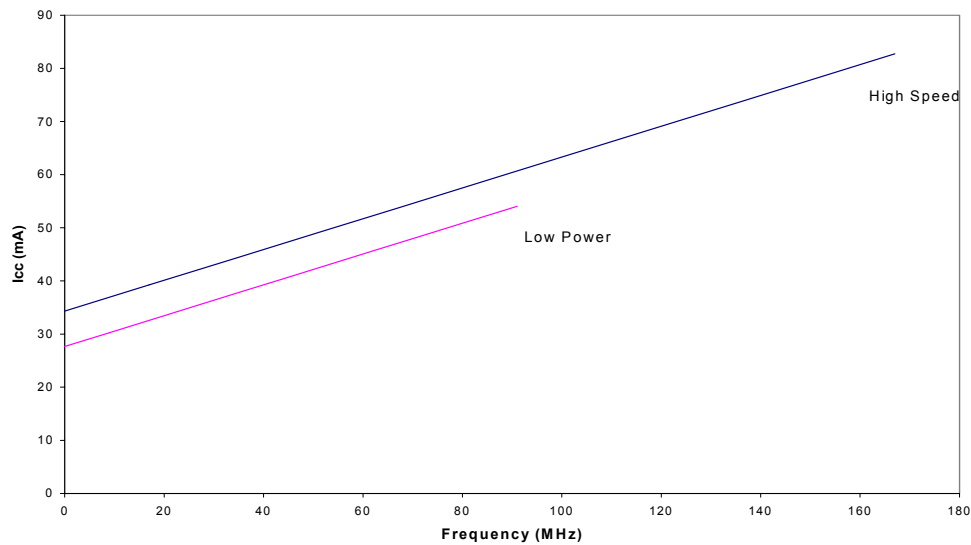
Power Consumption

Typical 5.0V Power Consumption CY37032

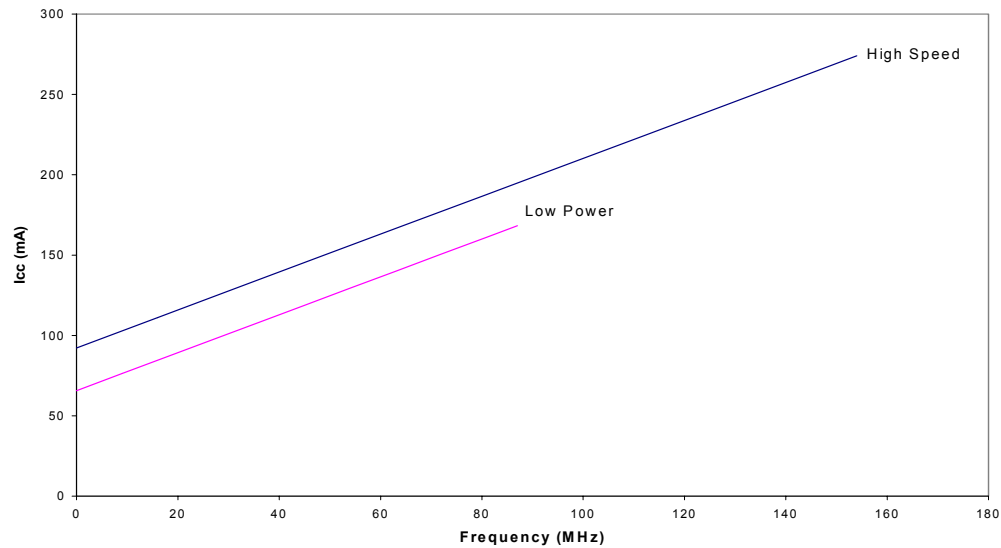


The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 5.0V, T_A = Room Temperature

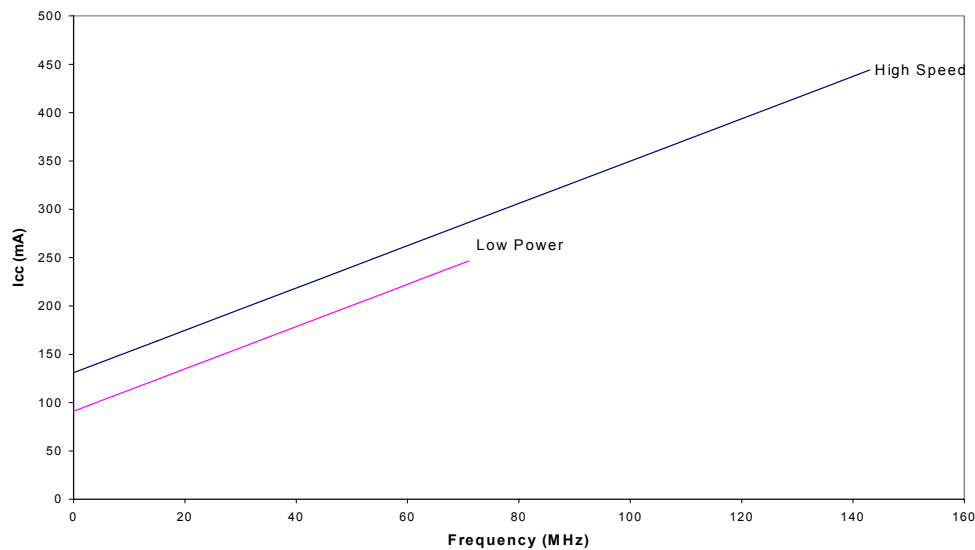
CY37064



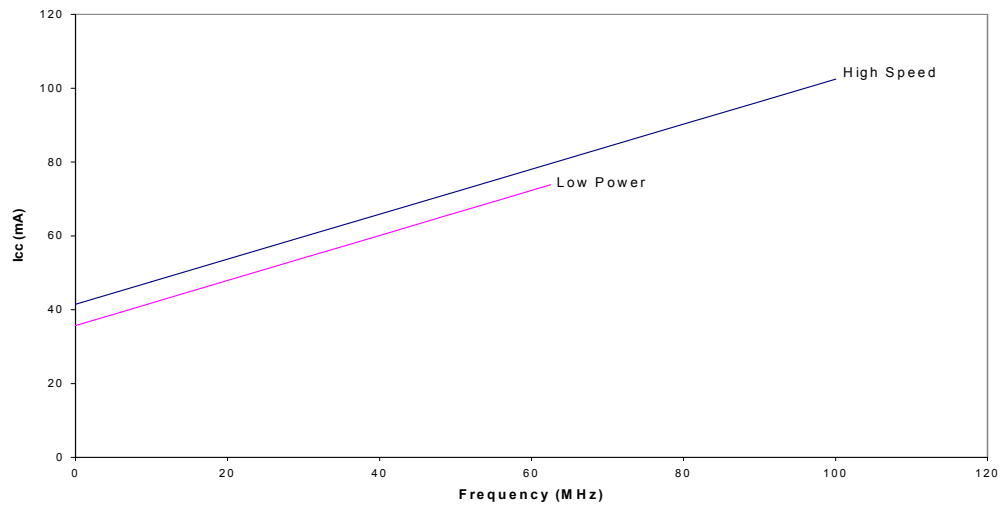
The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
V_{CC} = 5.0V, T_A = Room Temperature

Typical 5.0V Power Consumption (continued)
CY37256


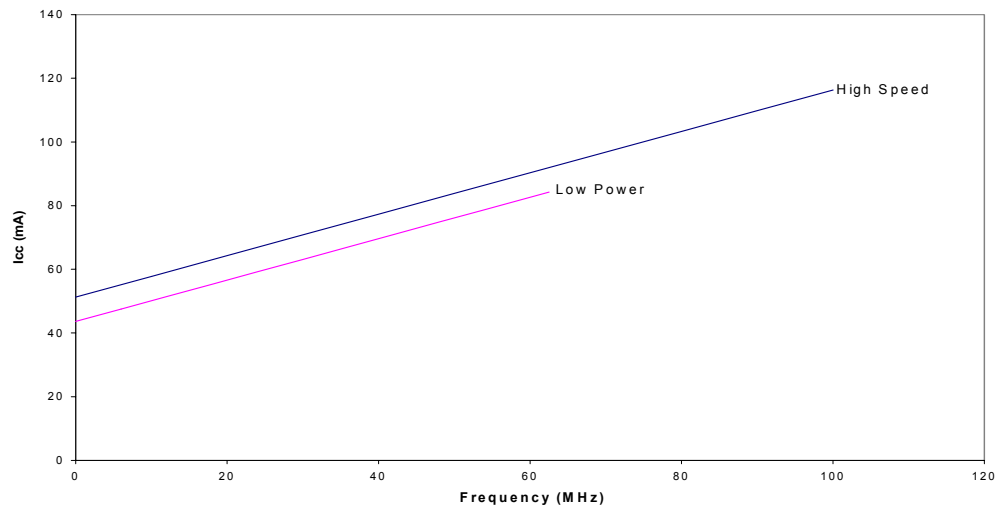
The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 5.0V$, $T_A = \text{Room Temperature}$

CY37384


The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 5.0V$, $T_A = \text{Room Temperature}$

Typical 3.3V Power Consumption (continued)
CY37192V


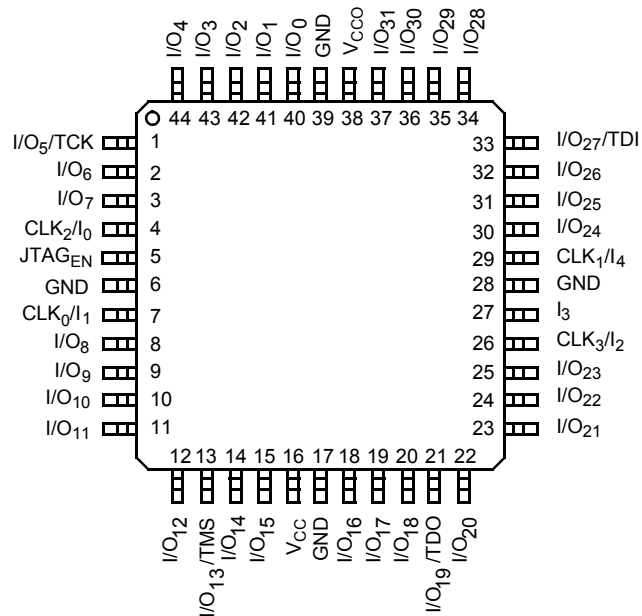
The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 3.3V$, $T_A = \text{Room Temperature}$

CY37256V


The typical pattern is a 16-bit up counter, per logic block, with outputs disabled.
 $V_{CC} = 3.3V$, $T_A = \text{Room Temperature}$

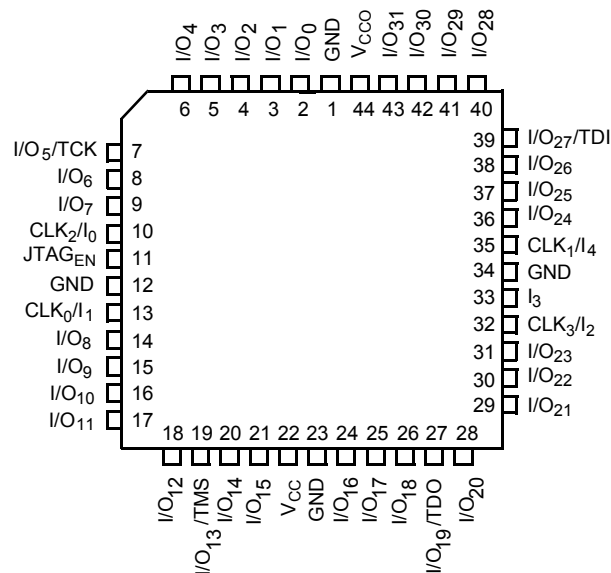
44-pin TQFP (A44)

Top View



44-pin PLCC (J67) / CLCC (Y67)

Top View

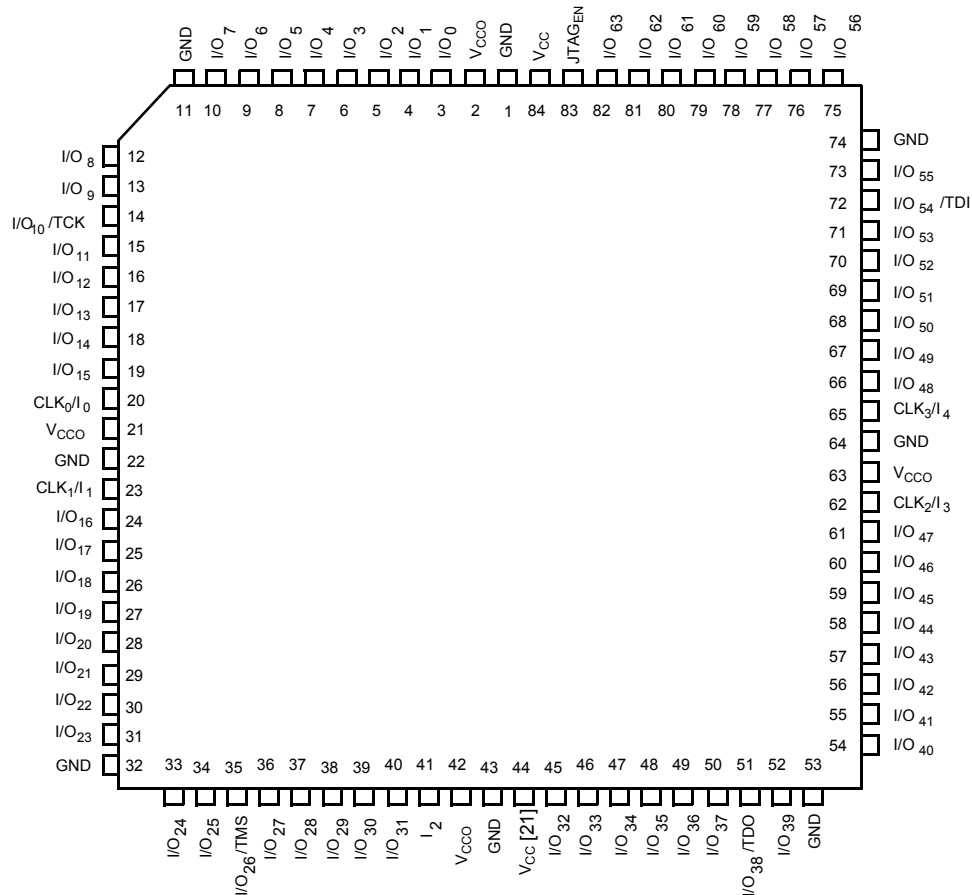


Pin Configurations^[20] (continued)
48-ball Fine-Pitch BGA (BA50)
Top View

	1	2	3	4	5	6	7	8
A	I/O ₅ TCK	V _{CC}	I/O ₃	I/O ₁	I/O ₃₁	I/O ₃₀	V _{CC}	I/O ₂₇ TDI
B	V _{CC}	I/O ₄	I/O ₂	I/O ₀	I/O ₂₉	I/O ₂₈	I/O ₂₆	CLK ₁ /I ₄
C	CLK ₂ /I ₀	I/O ₇	I/O ₆	GND	GND	I/O ₂₅	I/O ₂₄	I ₃
D	JTAG _{EN}	I/O ₈	I/O ₉	GND	GND	I/O ₂₂	I/O ₂₃	CLK ₃ /I ₂
E	CLK ₀ /I ₁	I/O ₁₂	I/O ₁₁	I/O ₁₀	I/O ₁₆	I/O ₂₀	I/O ₂₁	V _{CC}
F	I/O ₁₃ TMS	V _{CC}	I/O ₁₄	I/O ₁₅	I/O ₁₇	I/O ₁₈	V _{CC}	I/O ₁₉ TDO

Note:

20. For 3.3V versions (Ultra37000V), V_{CCO} = V_{CC}.

84-lead PLCC (J83) / CLCC (Y84)
Top View

Note:

21. This pin is a N/C, but Cypress recommends that you connect it to V_{CC} to ensure future compatibility.

Pin Configurations^[20] (continued)
388-Lead PBGA (BG388)
Top View

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26
A	GND	GND	I/O ₁₉	I/O ₁₅	I/O ₁₃	I/O ₃₄	I/O ₃₁	I/O ₂₈	I/O ₂₅	I/O ₁₀	I/O ₇	I/O ₄	I/O ₁	I/O ₂₆₃	I/O ₂₆₀	I/O ₂₅₇	I/O ₂₅₄	I/O ₂₃₉	I/O ₂₃₇	I/O ₂₃₂	I/O ₂₂₉	I/O ₂₅₀	I/O ₂₄₈	I/O ₂₄₄	GND	GND
B	GND	NC	I/O ₁₈	I/O ₁₇	I/O ₁₄	I/O ₃₅	I/O ₃₂	I/O ₂₉	I/O ₂₆	I/O ₁₁	I/O ₈	I/O ₅	I/O ₂	V _{CC}	I/O ₂₆₁	I/O ₂₅₈	I/O ₂₅₅	I/O ₂₅₂	I/O ₂₃₄	I/O ₂₃₁	I/O ₂₂₈	I/O ₂₄₉	I/O ₂₄₆	I/O ₂₄₅	I/O ₂₄₀	GND
C	I/O ₂₃	I/O ₃₈	I/O ₃₇	I/O ₁₆	I/O ₁₂	I/O ₃₃	I/O ₃₀	I/O ₂₇	I/O ₂₄	I/O ₉	I/O ₆	I/O ₃	I/O ₀	I/O ₂₆₂	I/O ₂₅₉	I/O ₂₅₆	I/O ₂₅₃	I/O ₂₃₈	I/O ₂₃₅	I/O ₂₃₃	I/O ₂₃₀	I/O ₂₅₁	I/O ₂₄₇	I/O ₂₂₅	I/O ₂₂₄	I/O ₂₂₇
D	I/O ₃₉	I/O ₄₀	I/O ₃₆	NC	NC	I/O ₂₁	I/O ₂₀	V _{CCO}	V _{CCO}	NC	GND	GND	V _{CCO}	V _{CCO}	GND	GND	NC	V _{CCO}	V _{CCO}	I/O ₂₃₆	I/O ₂₄₃	NC	NC	I/O ₂₂₆	I/O ₂₂₂	I/O ₂₂₃
E	I/O ₄₂	TCK	I/O ₄₁	NC																			NC	TDI	I/O ₂₂₁	I/O ₂₂₀
F	I/O ₄₅	I/O ₄₄	I/O ₄₃	I/O ₂₂																			I/O ₂₄₂	I/O ₂₁₉	I/O ₂₁₈	I/O ₂₁₇
G	I/O ₄₈	I/O ₄₇	I/O ₄₆	I/O ₆₃																			I/O ₂₄₁	I/O ₂₁₆	I/O ₂₁₅	I/O ₂₁₄
H	I/O ₄₉	I/O ₅₀	I/O ₅₁	V _{CCO}																			V _{CCO}	I/O ₂₁₁	I/O ₂₁₂	I/O ₂₁₃
J	I/O ₅₂	I/O ₅₃	I/O ₅₄	V _{CCO}																			V _{CCO}	I/O ₂₀₈	I/O ₂₀₉	I/O ₂₁₀
K	I/O ₅₅	I/O ₅₆	I/O ₅₇	NC																			NC	I/O ₂₀₅	I/O ₂₀₆	I/O ₂₀₇
L	I/O	I/O ₅₉	I/O ₅₈	GND																			GND	I/O ₂₀₄	I/O ₁₉₇	I/O ₁₉₇
M	I/O ₆₁	I/O ₆₀	I/O	GND																			GND	I/O	I/O ₂₀₃	I/O ₂₀₂
N	I/O ₆₄	V _{CC}	I/O ₆₂	V _{CCO}																			V _{CCO}	I/O ₂₀₁	I/O ₂₀₀	I/O ₁₉₉
P	I/O ₆₅	I/O ₆₆	I/O ₆₇	V _{CCO}																			V _{CCO}	I/O ₁₉₆	V _{CC}	I/O ₁₉₈
R	I/O ₆₈	I/O ₆₉	I/O ₇₀	GND																			GND	I/O ₁₉₃	I/O ₁₉₄	I/O ₁₉₅
T	I/O ₇₁	I/O ₈₄	I/O ₈₅	GND																			GND	I/O ₁₇₈	I/O ₁₇₉	I/O ₁₉₂
U	I/O ₈₈	I/O ₈₇	I/O ₈₆	NC																			NC	I/O ₁₇₇	I/O ₁₇₆	I/O ₁₇₅
V	I/O ₉₁	I/O ₉₀	I/O ₈₉	V _{CCO}																			V _{CCO}	I/O ₁₇₄	I/O ₁₇₃	I/O ₁₇₂
W	I/O ₉₄	I/O ₉₃	I/O ₉₂	V _{CCO}																			V _{CCO}	I/O ₁₇₁	I/O ₁₇₀	I/O ₁₆₉
Y	I/O ₉₅	I/O ₇₂	I/O ₇₃	I/O ₁₁₀																			I/O ₁₅₃	I/O ₁₉₀	I/O ₁₉₁	I/O ₁₆₈
AA	I/O ₇₄	I/O ₇₅	I/O ₇₆	I/O ₁₁₁																			I/O ₁₅₂	I/O ₁₈₇	I/O ₁₈₈	I/O ₁₈₉
AB	I/O ₇₇	I/O ₇₈	I/O ₇₉	NC																			NC	I/O ₁₈₄	I/O ₁₈₅	I/O ₁₈₆
AC	I/O ₈₁	I/O ₈₀	I/O ₁₀₈	NC	NC	I/O ₁₁₂	I/O ₁₁₃	V _{CCO}	V _{CCO}	NC	GND	GND	V _{CCO}	V _{CCO}	GND	GND	NC	V _{CCO}	V _{CCO}	I/O ₁₅₀	I/O ₁₅₁	NC	NC	I/O ₁₅₅	I/O ₁₈₃	I/O ₁₈₂
AD	I/O ₁₀₉	I/O ₈₂	I/O ₈₃	I/O ₁₁₇	I/O ₉₇	I/O ₁₀₀	I/O ₁₀₂	I/O ₁₀₅	I/O ₁₂₀	I/O ₁₂₃	I/O ₁₂₆	I/O ₁₂₉	I/O	I/O ₁₃₃	I/O ₁₃₆	I/O ₁₃₉	I/O ₁₄₂	I/O ₁₅₇	I/O ₁₅₉	I/O ₁₆₁	I/O ₁₆₃	I/O ₁₆₆	I/O ₁₄₆	I/O ₁₈₀	I/O ₁₈₁	I/O ₁₅₄
AE	GND	NC	I/O ₁₁₅	I/O ₁₁₆	I/O ₁₁₉	I/O ₉₈	I/O ₁₀₁	I/O ₁₀₃	I/O ₁₀₆	I/O ₁₂₁	I/O ₁₂₄	I/O ₁₂₇	V _{CC}	I/O ₁₃₀	I/O ₁₃₄	I/O ₁₃₇	I/O ₁₄₀	I/O ₁₄₃	I/O ₁₆₀	I/O ₁₆₂	I/O ₁₆₅	I/O ₁₄₄	I/O ₁₄₇	I/O ₁₄₈	NC	GND
AF	GND	GND	I/O ₁₁₄	I/O ₁₁₈	I/O ₉₆	I/O ₉₉	TMS	I/O ₁₀₄	I/O ₁₀₇	I/O ₁₂₂	I/O ₁₂₅	I/O ₁₂₈	I/O ₁₃₁	I/O ₁₃₂	I/O ₁₃₅	I/O ₁₃₈	I/O ₁₄₁	I/O ₁₅₆	I/O ₁₅₈	TDO	I/O ₁₆₄	I/O ₁₆₇	I/O ₁₄₅	I/O ₁₄₉	GND	GND

5.0V Ordering Information (continued)

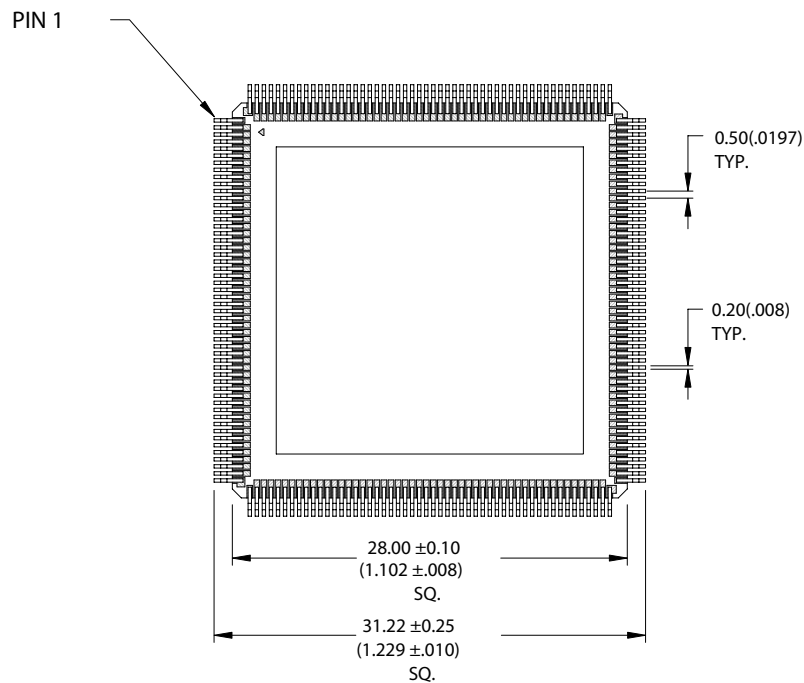
Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
512	125	CY37512P208-125NC	N208	208-Lead Plastic Quad Flat Pack	Commercial
		CY37512P256-125BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37512P352-125BGC	BG388	388-Ball Plastic Ball Grid Array	
	100	CY37512P208-100NC	N208	208-Lead Plastic Quad Flat Pack	Commercial
		CY37512P256-100BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37512P352-100BGC	BG388	388-Ball Plastic Ball Grid Array	
		CY37512P208-100NI	N208	208-Lead Plastic Quad Flat Pack	Industrial
		CY37512P256-100BGI	BG292	292-Ball Plastic Ball Grid Array	
		CY37512P352-100BGI	BG388	388-Ball Plastic Ball Grid Array	
		5962-9952502QZC	U208	208-Lead Ceramic Quad Flat Pack	Military
	83	CY37512P208-83NC	N208	208-Lead Plastic Quad Flat Pack	Commercial
		CY37512P256-83BGC	BG292	292-Ball Plastic Ball Grid Array	
		CY37512P352-83BGC	BG388	388-Ball Plastic Ball Grid Array	
		CY37512P208-83NI	N208	208-Lead Plastic Quad Flat Pack	Industrial
		CY37512P256-83BGI	BG292	292-Ball Plastic Ball Grid Array	
		CY37512P352-83BGI	BG388	388-Ball Plastic Ball Grid Array	
		5962-9952501QZC	U208	208-Lead Ceramic Quad Flat Pack	Military

3.3V Ordering Information

Macrocells	Speed (MHz)	Ordering Code	Package Name	Package Type	Operating Range
32	143	CY37032VP44-143AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37032VP44-143AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032VP48-143BAC	BA50	48-Ball Fine Pitch Ball Grid Array	
	100	CY37032VP44-100AC	A44	44-Lead Thin Quad Flat Pack	Commercial
		CY37032VP44-100AXC	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032VP48-100BAC	BA50	48-Ball Fine Pitch Ball Grid Array	
		CY37032VP44-100AI	A44	44-Lead Thin Quad Flat Pack	Industrial
		CY37032VP44-100AXI	A44	44-Lead Lead Free Thin Quad Flat Pack	
		CY37032VP48-100BAI	BA50	48-Ball Fine Pitch Ball Grid Array	
		CY37032VP44-100JI	J67	44-Lead Plastic Leaded Chip Carrier	
		CY37032VP44-100JXI	J67	44-Lead Lead Free Plastic Leaded Chip Carrier	

Package Diagrams (continued)

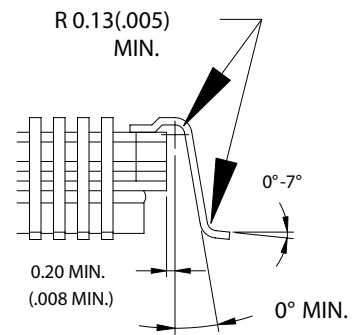
208-Lead Ceramic Quad Flatpack (Cavity Up) U208



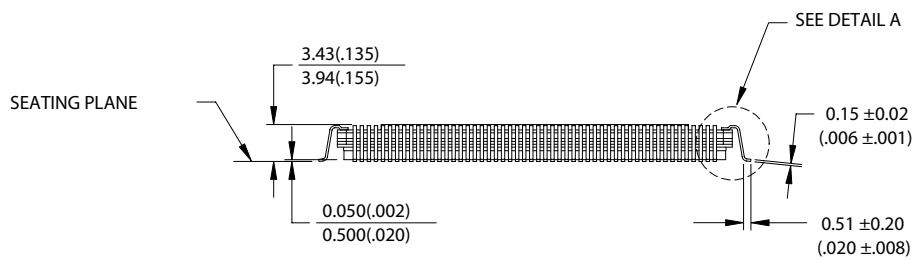
DIMENSIONS IN MM (INCH)

REFERENCE JEDEC: N/A

PKG. WEIGHT: 6-7gms



DETAIL A



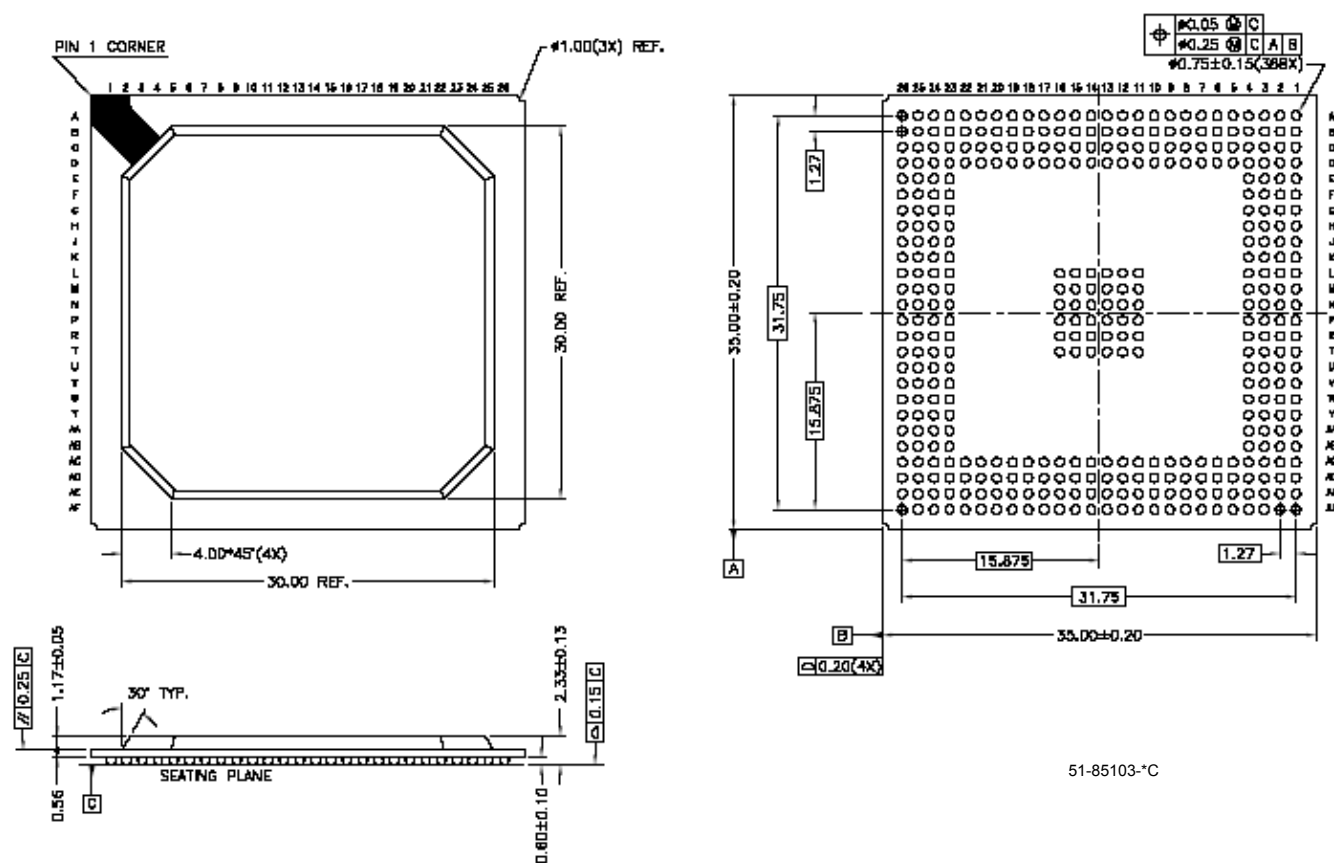
51-80105-B



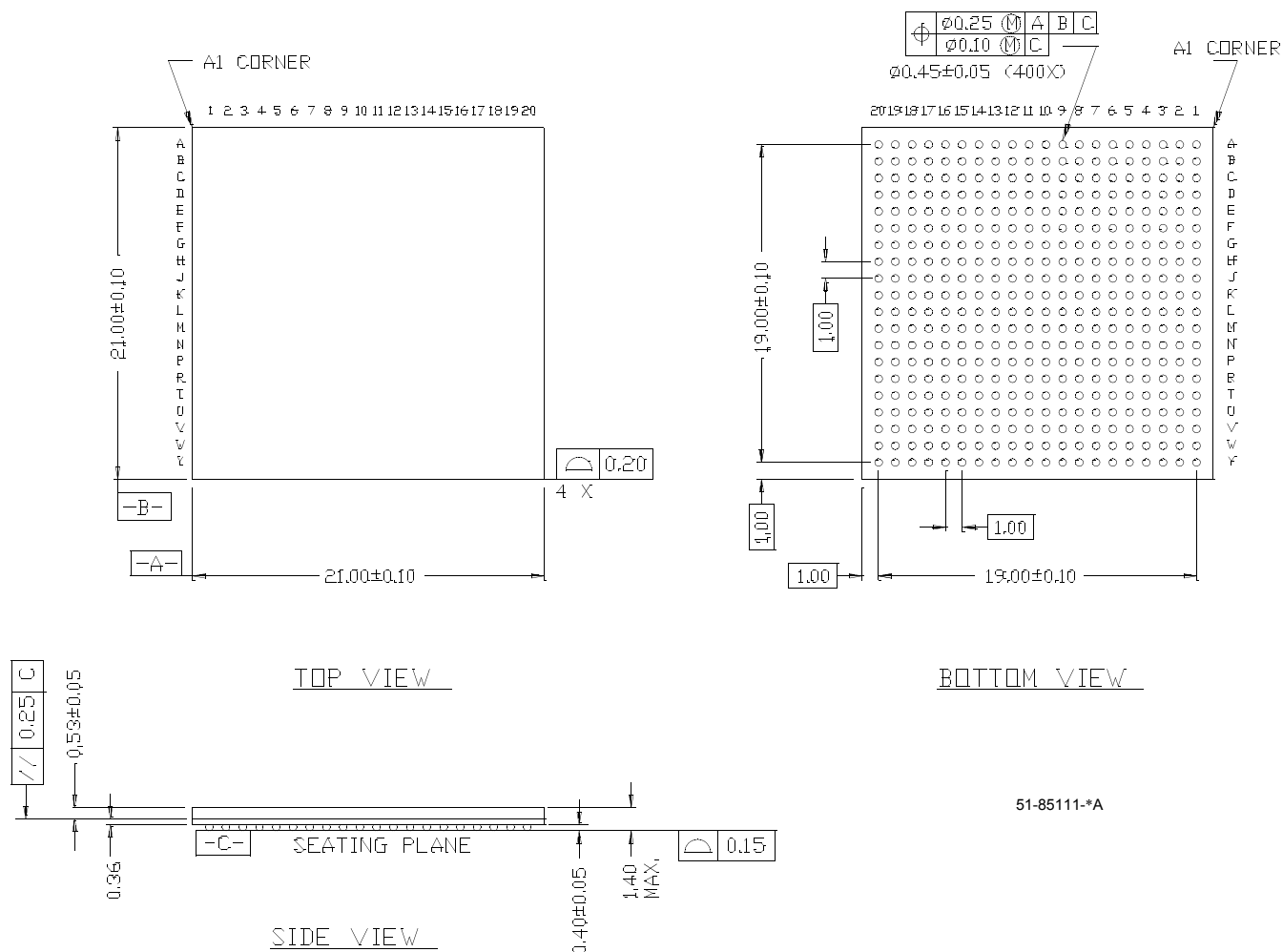
Ultra37000 CPLD Family

Package Diagrams (continued)

388-Ball Plastic Ball Grid Array PBGA (35 x 35 x 2.33 mm) BG388



51-85103-*C

Package Diagrams (continued)
400-Ball FBGA (21 x 21 x 1.4 mm) BB400


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Addendum
3.3V Operating Range

(CY37064VP100-143AC, CY37064VP100-143BBC, CY37064VP44-143AC, CY37064VP48-143BAC)

Range	Ambient Temperature ^[2]	Junction Temperature	V _{CC}
Commercial	0°C to +70°C	0°C to +90°C	3.3V ± 0.16V

Document History Page

Document Title: Ultra37000 CPLD Family 5V, 3.3V, ISR™ High-Performance CPLDs Document Number: 38-03007				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	106272	04/18/01	SZV	Change from Spec number: 38-00475 to 38-03007
*A	124942	03/21/03	OOR	Updated 3.3V V _{CC} requirements for –144 speeds Added an Addendum
*B	126262	05/09/03	TEH	Changed pinout for CY37128V BB100 package
*C	128125	07/16/03	HOM	Obsoleted following 3.3V PLCC packaged devices: CY37032VP44-143JC CY37032VP44-100JC CY37032VP44-100JI CY37064VP44-143JC CY37064VP84-143JC CY37064VP44-100JC CY37064VP84-100JC CY37064VP44-100JI CY37064VP84-100JI CY37128VP84-125JC CY37128VP84-83JC CY37128VP84-83JI
*D	282709	See ECN	YDT	Changed package diagrams and labels for consistency Added Lead (Pb)-free logo on first page, as well as a note in Features Added Lead (Pb)-free package diagram labels Added Lead-free Parts to Ordering Information CY37032P44-200AXC, CY37032P44-200JXC, CY37032P44-154AXI, CY37032P44-154JXI, CY37032P44-125AXC, CY37032P44-125JXC, CY37064P44-200AXC, CY37064P44-200JXC, CY37064P100-200AXC, CY37064P44-154AXI, CY37064P44-154JXI, CY37064P44-125AXC, CY37064P44-125JXC, CY37064P100-125AXC, CY37064P44-125AXI, CY37064P100-125AXI, CY37128P84-167JXC, CY37128P100-167AXC, CY37128P160-167AXC, CY37128P84-125JXC, CY37128P100-125AXC, CY37128P160-125AXC, CY37128P84-125JXI, CY37128P100-125AXI, CY37128P160-125AXI, CY37128P84-100JXC, CY37128P100-100AXC, CY37128P160-100AXC, CY37128P100-100AXI, CY37192P160-154AXC, CY37192P160-125AXC, CY37192P160-125AXI, CY37192P160-83AXC, CY37192P160-83AXI, CY37256P160-154AXC, CY37256P160-125AXC, CY37256P160-125AXI, CY37256P160-83AXC, CY37256P160-83AXI, CY37032VP44-143AXC, CY37032VP44-100AXC, CY37032VP44-100AXI, CY37032VP44-100JXI, CY37064VP44-143AXC, CY37064VP100-143AXC, CY37064VP44-100AXC, CY37064VP100-100AXC, CY37064VP44-100AXI, CY37064VP100-100AXI, CY37128VP100-125AXC, CY37128VP160-125AXC, CY37128VP160-125AXI, CY37128VP100-83AXC, CY37128VP160-83AXC, CY37128VP100-83AXI, CY37128VP160-83AXI, CY37192VP160-100AXC, CY37192VP160-66AXC, CY37256VP160-100AXC, CY37256VP160-100AXI, CY37256VP160-66AXC
*E	321635	See ECN	PCX	Added Package Diagram BG292 Updated all PBGA package type information (BG292 & BG388)